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*PATENT* 03371-P0005A LHR

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants	Lynn David Bollinger, et al.
Serial No. 09/693,117	Filing Date: October 20, 2000
Title of Application	Method for Rapid Thermal Processing of Substrates
Group Art Unit 2812	2812

#9 4-18-02 Reduce

Assistant Commissioner for Patents Washington, DC 20231

### **Preliminary Amendment**

Dear Sir:

### **Amendment Revisions**

# RECEIVED APR-2 2002 IC 2800 MAIL ROOM

## **In the Specification**

Please substitute the first paragraph on page 33 through the third paragraph on page 34 with the following paragraphs.

# Clean Version of Each Replacement Paragraph of the Specification



For this approximate physical model, we consider the substrate as three equal layers each of thickness  $\Delta h/3$ . We estimate the temperature rise of the top, directly heated layer and then compare this to an estimate of the heat transferred through the

<u>Mailing Certificate</u>: I hereby certify that this correspondence is today being deposited with the U.S. Postal Service as *First Class Mail* in an envelope addressed to: Commissioner for Patents and Trademarks; Washington, DC 20231.

March 19, 2002

Caroline Gahagan